

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.0128	100.0	0.26839
			Subtotal	0.0128	100	0.26839
Die	Doped silicon	Silicon (Si)	7440-21-3	0.30036	100.0	6.3
			Subtotal	0.30036	100	6.3
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.02756	5.0	0.83
	Silver alloy	Silver (Ag)	7440-22-4	0.00551	1.5	0.42
	Lead alloy	Lead (Pb)	7439-92-1	0.2425	93.5	15.42
			Subtotal	0.27557	100	16.67
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.20063	100.0	4.20829
			Subtotal	0.20063	100	4.20829
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00701	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.00467	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.00701	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.02569	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	23.30661	99.81	488.8594
			Subtotal	23.35099	100	489.79001
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.24634	100.0	5.167
			Subtotal	0.24634	100	5.167
Mould Compound	Polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	2.2684	3.0	47.58
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	4.5368	6.0	95.16
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	7.56133	10.0	158.6
	Carbon Black	Carbon black	1333-86-4	0.37807	0.5	7.93
	Filler	Misc. Silica compounds (generic)	14808-60-7	58.9784	78.0	1237.08
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	1.89033	2.5	39.65
			Subtotal	75.61333	100	1586
			Total	100.00002	100	2108.51369

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